Integra Technologies has been Acquired by Micross Components Inc.

We're excited to announce that on January 15th, 2025, Integra Technologies, provider of Outsourced Semiconductor Assembly and Test (OSAT) and post-processing services focused on high-reliability applications and end markets, has been acquired by Micross Components Inc., provider of end-to-end microelectronic services and proprietary product solutions. The acquisition of Integra further positions Micross as a leader in United States-based OSAT services and broadens Micross' portfolio of high-reliability microelectronic services and products. Micross purchase of Integra was structured as an acquisition of all outstanding ESOP Shares.

As a valued customer, we appreciate your business and the trust you place in Integra Technologies to support your Die & Wafer Prep, Testing, and other OSAT requirements. We are reaching out to assure you that Integra will continue to provide you with the same high-quality service you depend on. Your business will also have access to greater value with one source, one solution access to an enhanced suite of microelectronic services and proprietary Hi Rel Power, RF/MMwave, and Data products.

Integra Technologies will continue to operate independently, as a wholly owned subsidiary of Micross and continue to provide you with exceptional service from our **Wichita, KS (CAGE: 1SRY1)** and **Milpitas, CA (CAGE: 061F4)** operations. CAGE codes for Integra operations; existing business contacts; and current payment details will not change. There is no need to change or update vendor account information in you purchasing systems.

In addition to the current products and services Integra Technologies has provided, we will now be able to offer you the expanded capabilities of the total Micross portfolio. With these combined capabilities, Integra Technologies is now even better positioned to serve the onshore semiconductor ecosystem for all microelectronic needs of the Hi Rel aerospace, defense, medical, and industrial markets fully encompassing, bare die and wafer processing, advanced interconnect technologies, component modification, testing, qualification, counterfeit mitigation, fully packaged and assembled modules, as well as a myriad of products and program sustainment solutions.